

# N0434N

### R07DS0556EJ0100 Rev.1.00 Nov 07, 2011

## N-CHANNEL MOSFET FOR SWITCHING

### **Description**

The N0434N is N-channel MOS Field Effect Transistor designed for high current switching applications.

### **Features**

• Low on-state resistance

$$R_{DS (on)} = 3.7 \text{ m}\Omega \text{ MAX.} (V_{GS} = 10 \text{ V}, I_D = 50 \text{ A})$$

• Low input capacitance

$$C_{iss} = 5550 \text{ pF TYP.} (V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V})$$

• High current

$$I_{D(DC)} = \pm 100 \text{ A}$$

• RoHS Compliant

## **Ordering Information**

Part No.	Lead Plating	Packing	Package
N0434N-S23-AY *1	Pure Sn (Tin)	Tube	TO-262
		50 p/tube	1.8 g TYP.

Note: \*1. Pb-free (This product does not contain Pb in the external electrode.)

## Absolute Maximum Ratings ( $T_A = 25$ °C, all terminals are connected)

Item	Symbol	Ratings	Unit
Drain to Source Voltage (V <sub>GS</sub> = 0 V)	V <sub>DSS</sub>	40	V
Gate to Source Voltage (V <sub>DS</sub> = 0 V)	$V_{GSS}$	±20	V
Drain Current (DC)	I <sub>D(DC)</sub>	±100	Α
Drain Current (pulse) *1	I <sub>D(pulse)</sub>	±400	Α
Total Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>T1</sub>	119	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T2</sub>	1.5	W
Channel Temperature	T <sub>ch</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C
Single Avalanche Current *2	I <sub>AS</sub>	55	Α
Single Avalanche Energy *2	E <sub>AS</sub>	300	mJ

## **Thermal Resistance**

Channel to Case (Drain) Thermal Resistance  $R_{th(ch-C)}$  1.05 °C/W Channel to Ambient Thermal Resistance \*2  $R_{th(ch-A)}$  83.3 °C/W

Notes: \*1. PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

\*2. Starting  $T_{ch}$  = 25°C,  $R_G$  = 25  $\Omega$ ,  $V_{DD}$  = 25 V,  $V_{GS}$  = 20  $\rightarrow$  0 V, L = 100  $\mu H$ 

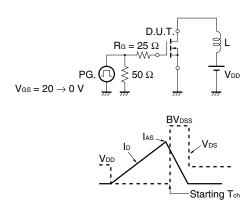
# Electrical Characteristics ( $T_A = 25$ °C, all terminals are connected)

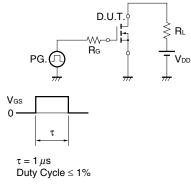
Item	Symbol	MIN.	TYP.	MAX.	Unit	Test Conditions
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			1	μΑ	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$
Gate Leakage Current	I <sub>GSS</sub>			±100	nA	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$
Gate to Source Cut-off Voltage	$V_{GS(off)}$	2.0		4.0	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward Transfer Admittance *1	y <sub>fs</sub>	26			S	$V_{DS} = 10 \text{ V}, I_{D} = 50 \text{ A}$
Drain to Source On-state Resistance *1	R <sub>DS(on)</sub>		2.7	3.7	mΩ	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 50 A
Input Capacitance	C <sub>iss</sub>		5550		pF	V <sub>DS</sub> = 25 V,
Output Capacitance	Coss		580		pF	$V_{GS} = 0 V$ ,
Reverse Transfer Capacitance	C <sub>rss</sub>		320		pF	f = 1 MHz
Turn-on Delay Time	t <sub>d(on)</sub>		29.0		ns	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 50 A,
Rise Time	t <sub>r</sub>		15.0		ns	V <sub>GS</sub> = 10 V,
Turn-off Delay Time	$t_{\text{d(off)}}$		64.0		ns	$R_G = 0 \Omega$
Fall Time	t <sub>f</sub>		13.0		ns	
Total Gate Charge	$Q_G$		100		nC	$V_{DD} = 32 V$ ,
Gate to Source Charge	$Q_{GS}$		26		nC	$V_{GS}$ = 10 $V$ ,
Gate to Drain Charge	$Q_{GD}$		32		nC	I <sub>D</sub> = 100 A
Body Diode Forward Voltage *1	$V_{F(S-D)}$			1.5	V	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0 V
Reverse Recovery Time	trr		40		ns	$I_F = 50 \text{ A}, V_{GS} = 0 \text{ V},$
Reverse Recovery Charge	Qrr		44		nC	di/dt = 100 A/μs

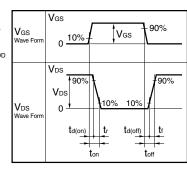
Note: \*1. Pulsed

## **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

## TEST CIRCUIT 2 SWITCHING TIME





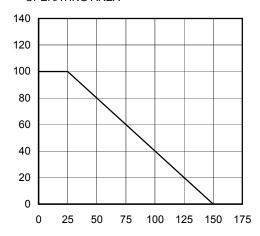


### **TEST CIRCUIT 3 GATE CHARGE**

dT - Percentage of Rated Power - %

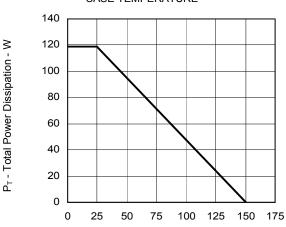
## Typical Characteristics ( $T_A = 25^{\circ}C$ )

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



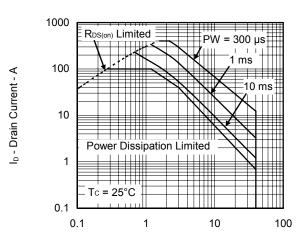
T<sub>C</sub> - Case Temperature - °C

# TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



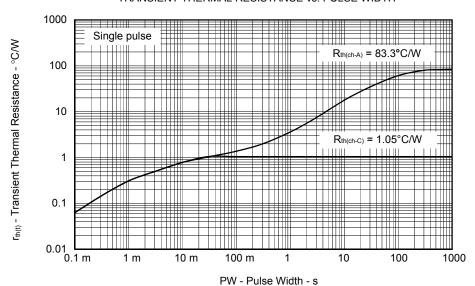
T<sub>C</sub> - Case Temperature - °C

#### FORWARD BIAS SAFE OPERATING AREA



 $V_{\text{DS}}$  - Drain to Source Voltage - V

### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

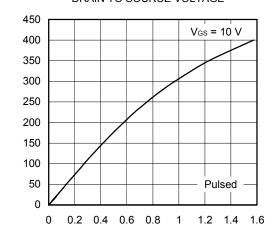


lo - Drain Current - A

V<sub>GS(off)</sub> - Gate to Source Cut-off Voltage - V

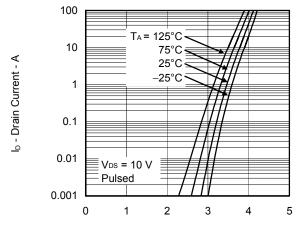
 $R_{\text{DS(on)}}$  - Drain to Source On-state Resistance -  $m\Omega$ 

# DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



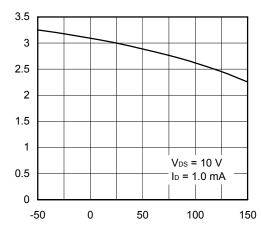
 $V_{\text{DS}}$  - Drain to Source Voltage - V

#### FORWARD TRANSFER CHARACTERISTICS



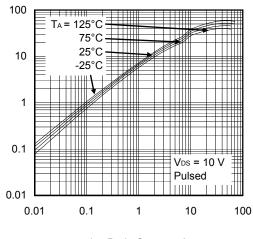
V<sub>GS</sub> - Gate to Source Voltage - V

# GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



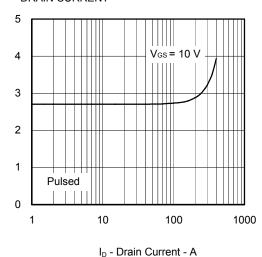
 $T_{\text{ch}}$  - Channel Temperature -  $^{\circ}C$ 

# FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

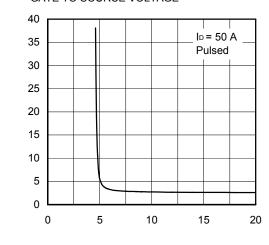


I<sub>D</sub> - Drain Current - A

# DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



# DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



 $V_{\text{GS}}$  - Gate to Source Voltage - V

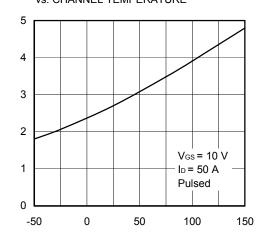
 $R_{\text{DS(on)}}$  - Drain to Source On-state Resistance -  $m\Omega$ 

y<sub>s</sub> | - Forward Transfer Admittance - S

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - Drain to Source On-state Resistance -  $m\Omega$ 

t<sub>d (on)</sub>, t<sub>r</sub>, t<sub>d (off)</sub>, t<sub>f</sub> - Switching Time - ns

# DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



T<sub>ch</sub> - Channel Temperature - °C

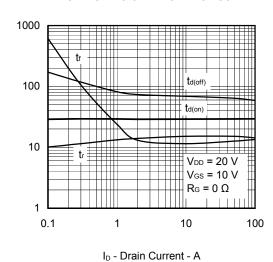
## 

10000

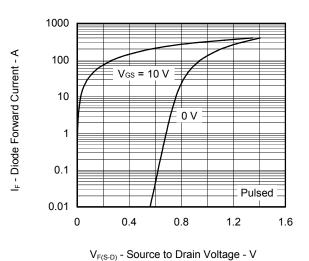
V<sub>DS</sub> - Drain to Source Voltage - V

CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

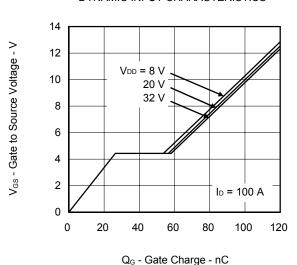
#### SWITCHING CHARACTERISTICS



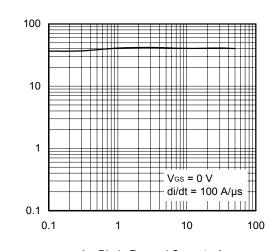
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



#### DYNAMIC INPUT CHARACTERISTICS



REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

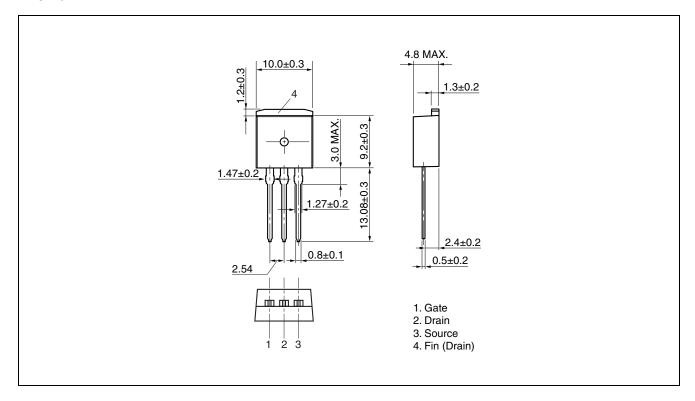


I<sub>F</sub> - Diode Forward Current - A

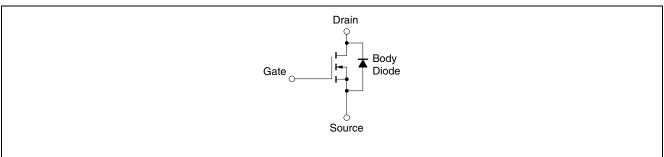
t<sub>rr</sub> - Reverse Recovery Time - ns

## Package Drawing (Unit: mm)

#### TO-262



## **Equivalent Circuit**



Remark

Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

**Revision History** 

## N0434N Data Sheet

		Description		
Rev.	Date	Page	Summary	
1.00	Nov 07, 2011	_	First Edition Issued	

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